

S/N 09/854,539

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

Applicant: Intel Corporation et al.

Serial No.: 09/854,539

Filed: May 14, 2001

Title: POLYMERIC ENCAPSULATION MATERIAL
WITH FIBROUS FILLER FOR USE IN
MICROELECTRONIC CIRCUIT PACKAGING

Customer Number: 21186



Examiner: Alonzo Chambliss

Group Art Unit: 2814

Docket No.: 884.415US1

RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on February 8, 2006. Please consider the remarks as follows.